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DMA30401

Silicon PNP epitaxial planar type (Tr1)

Silicon PNP epitaxial planar type (Tr2)

For general amplification

Marking Symbol : A7

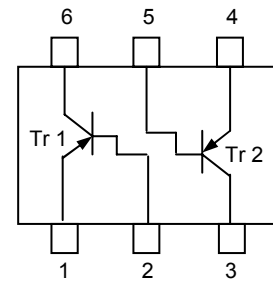
Package Code : SSSMini6-F2-B

Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

	Parameter	Symbol	Rating	Unit
Tr1 Tr2	Collector-base voltage (Emitter open)	VCBO	-60	V
	Collector-emitter voltage (Base open)	VCEO	-50	V
	Emitter-base voltage (Collector open)	VEBO	-7	V
	Collector current	IC	-100	mA
	Peak collector current	ICp	-200	mA
Overall	Total power dissipation *1	PT	125	mW
	Junction temperature	Tj	150	$^\circ\text{C}$
	Storage temperature	Tstg	-55 to +150	$^\circ\text{C}$

Note: 1. *1 Measuring on substrate at 17 mm × 10 mm × 1 mm

Internal Connection



Pin name

1.	Emitter(Tr1)	4.	Emitter(Tr2)
2.	Base(Tr1)	5.	Base(Tr2)
3.	Collector(Tr2)	6.	Collector(Tr1)

Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Tr1, Tr2

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = -10 μA , IE = 0	-60			V
Collector-emitter voltage (Base open)	VCEO	IC = -2 mA, IB = 0	-50			V
Emitter-base voltage (Collector open)	VEBO	IE = -10 μA , IC = 0	-7			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = -20 V, IE = 0			-0.1	μA
Collector-emitter cutoff current (Base open)	ICEO	VCE = -10 V, IB = 0			-100	μA
Forward current transfer ratio	hFE	VCE = -10 V, IC = -2mA	210		460	-
Collector-emitter saturation voltage	VCE(sat)	IC = -100 mA, IB = -10 mA		-0.2	-0.5	V
Transition frequency	fT	VCE = -10 V, IC = -2 mA		150		MHz
Collector output capacitance (Common base, input open circuited)	Cob	VCB = -10 V, IE = 0, f = 1 MHz		2		pF

Note: Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

Packing

Embossed type (Thermo-compression sealing) R specification : 10 000 pcs / reel

2010.3.1	2010.9.6	
Prepared	Revised	

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